Product / Package Information

Package	SOT 89
Body Size	
Lead Count	3
Terminal Finish	100Sn
MS Number	MS010593B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.83 E-02	87.7	877000	48.87	488716
Thermosets	Epoxy Resin	Proprietary	1.61 E-03	5.0	50000	2.79	27863
Thermosets	Phenol Resin	Proprietary	1.61 E-03	5.0	50000	2.79	27863
Thermosets	Epoxy Cresol Novolac	29690-82-2	6.45 E-04	2.0	20000	1.11	11145
Other inorganic materials	Carbon Black	1333-86-3	9.68 E-05	0.3	3000	0.17	1672
Subtotal			3.23 E-02	100	1000000	55.73	557259

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.92 E-02	99.87	998700	33.16	331645
Copper & its alloys	Iron	7439-89-6	1.92 E-05	0.10	1000	0.03	332
Copper & its alloys	Phosphorus	7723-14-0	5.77 E-06	0.03	300	0.01	100
Subtotal			1.92 E-02	100.00	1000000	33.21	332077

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.84 E-04	100.0	1000000	0.66	6629

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.72 E-03	100.0	1000000	6.42	64219

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.39 E-04	99.99	1000000	0.76	7582

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	8.28 E-04	100.0	1000000	1.43	14294

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.31 E-04	80	800000	1.44	14352
Thermosets	Epoxy Resin	Proprietary	1.56 E-04	15	150000	0.27	2691
Others	Curing agent & hardener	Proprietary	5.19 E-05	5	50000	0.09	897
Subtotal			1.04 E-03	100	1000000	1.79	17940

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.79 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	SOT 89
Body Size	
Lead Count	3
Terminal Finish	SnPb
MS Number	MS010572C

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.83 E-02	87.7	877000	48.87	488716
Thermosets	Epoxy Resin	Proprietary	1.61 E-03	5.0	50000	2.79	27863
Thermosets	Phenol Resin	Proprietary	1.61 E-03	5.0	50000	2.79	27863
Thermosets	Epoxy Cresol Novolac	29690-82-2	6.45 E-04	2.0	20000	1.11	11145
Other inorganic materials	Carbon Black	1333-86-3	9.68 E-05	0.3	3000	0.17	1672
Subtotal			3.23 E-02	100	1000000	55.73	557259

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.87 E-02	97.50	975000	32.38	323775
Copper & its alloys	Iron	7439-89-6	4.52 E-04	2.35	23500	0.78	7804
Copper & its alloys	Zinc	7440-66-6	2.31 E-05	0.12	1200	0.04	398
Copper & its alloys	Phosphorus	7723-14-0	5.77 E-06	0.03	300	0.01	100
Subtotal			1.92 E-02	100.00	1000000	33.21	332077

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.84 E-04	100.0	1000000	0.66	6629

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.16 E-03	85.00	850000	5.46	54587
Tin & its alloys	Lead	7439-92-1	5.58 E-04	15.00	150000	0.96	9633
Subtotal			3.72 E-03	100.0	1000000	6.42	64219

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.39 E-04	99.99	1000000	0.76	7582

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	8.28 E-04	100.0	1000000	1.43	14294

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.31 E-04	80.00	800000	1.44	14352
Other organic materials	bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	1.56 E-04	15.00	150000	0.27	2691
Other organic materials	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	2.60 E-05	2.50	25000	0.04	449
Other organic materials	Dapsone	80-08-0	2.60 E-05	2.50	25000	0.04	449
Subtotal			1.04 E-03	100	1000000	1.79	17940

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.79 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
AHEAD OF WHAT'S POSSIBLE™

ADI Proprietary